

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A electronic circuit apparatus comprising:

~~at least two wiring circuit boards each of which is a multilayered wiring board~~
mounted with at least two electronic components;

~~a polyimide wiring board mounted with at least one heat generating component;~~

~~a heat sink on which said wiring circuit boards are fixed, said heat sink having a higher heat conductivity than that those of said the multilayered wiring circuit boards board and the polyimide wiring board, wherein the multilayered wiring board is fixed to one surface of the heat sink via adhesive and the polyimide wiring board is fixed to another surface of the heat sink via a adhesive;~~

~~an external connection terminal to which the multilayered wiring board and/or the polyimide wiring board is electrically connected to said wiring circuit boards; and~~

~~a thermosetting resin composition with which the entire surfaces of said the multilayered wiring circuit boards board and the polyimide wiring board, a part of said the heat sink and a part of said the external connection terminal are integrally molded, wherein:~~

~~said wiring circuit boards on which all necessary electronic components are mounted in advance are fixed to the top and bottom of said heat sink via an adhesive layer.~~

2-6. (Canceled).

7. (Currently Amended) The electronic circuit apparatus according to claim 1, wherein a part of a passage for circulating a cooling medium is formed in an external layer of ~~said the~~ electronic circuit apparatus.

8. (Currently Amended) A structure for mounting ~~said the~~ electronic circuit apparatus of claim-6 7, wherein ~~said the~~ electronic circuit apparatus is fixed on the interior of an automatic transmission assembly of an automobile, and wherein said cooling medium is a transmission fluid.

9. (Currently Amended) A structure for mounting ~~said the~~ electronic circuit apparatus of claim-6 7, wherein ~~said the~~ electronic circuit apparatus is fixed on the interior of an engine compartment of an automobile, and wherein ~~said the~~ cooling medium is an engine cooling water.

10. (Currently Amended) A structure for mounting ~~said the~~ electronic circuit apparatus of claim-6 7, wherein ~~said the~~ electronic circuit apparatus is fixed on the interior of an engine intake pipe of an automobile, and wherein ~~said the~~ cooling medium is the air that passes in ~~said the~~ engine intake pipe.

11. (Currently Amended) A structure for mounting ~~said the~~ electronic circuit apparatus of claim-6 7, wherein at least two electronic circuit apparatuses are stacked on top of each other, and wherein ~~said the~~ passage for circulating cooling medium is ~~circulated~~ provided in the stacked electronic circuit apparatuses.

12. (Currently Amended) The electronic circuit apparatus according to claim 1, wherein ~~said the~~ adhesive layer is formed by a two-color printing process

~~employing comprises a heat-conducting paste containing a highly heat-conductive metal particle and/or a metal oxide particle, and an insulating organic paste, and wherein said heat-conductive paste is disposed immediately below where a bare silicon chip is mounted on said wiring circuit boards.~~

13. (Currently Amended) The electronic circuit apparatus according to claim 1, wherein ~~said the~~ heat sink is made of a metal compound with electrical conductivity, and wherein ~~said the~~ adhesive layer is formed by an insulating organic paste.

14. (Currently Amended) The electronic circuit apparatus according to claim ~~13~~ 1, wherein ~~said the~~ heat sink is made of a clad material containing a copper alloy or copper.

15. (Currently Amended) The electronic circuit apparatus according to claim ~~13~~ 1, wherein ~~said the~~ adhesive layer is made of a thermosetting resin composition containing an epoxy resin and an inorganic filler.

16. (Currently Amended) The electronic circuit apparatus according to claim 1, wherein ~~at least one of said the multilayered wiring circuit boards is a board comprises at least one~~ ceramic substrate.

17. (Canceled).

18. (New) The electronic circuit apparatus according to claim 1, wherein the polyimide wiring board is bent at least one end such that the polyimide wiring board

is fixed to the another surface of the heat sink via the adhesive and fixed at the at least one end to the one surface of the heat sink.

19. (New) The electronic circuit apparatus according to claim 18, wherein the multilayered wiring board and the polyimide wiring board are electrically connected.

20. (New) The electronic circuit apparatus according to claim 7, wherein the part of the passage for circulating a cooling medium is formed in the thermosetting resin composition.